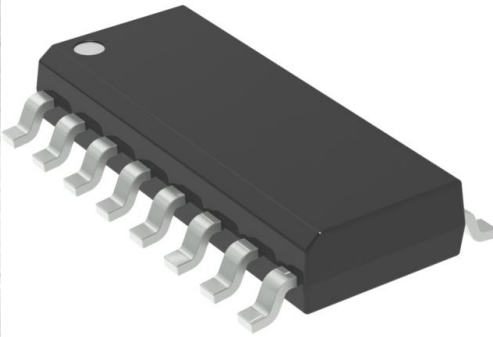


MC14532BDG Datasheet

www.digi-electronics.com



<https://www.DiGi-Electronics.com>

DiGi Electronics Part Number	MC14532BDG-DG
Manufacturer	onsemi
Manufacturer Product Number	MC14532BDG
Description	IC PRIORITY ENCOD 1 X 8:3 16SOIC
Detailed Description	Priority Encoder 1 x 8:3 16-SOIC



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.

Purchase and inquiry

Manufacturer Product Number:

MC14532BDG

Series:

4000B

Type:

Priority Encoder

Independent Circuits:

1

Voltage Supply Source:

Dual Supply

Operating Temperature:

-55°C ~ 125°C

Package / Case:

16-SOIC (0.154", 3.90mm Width)

Base Product Number:

MC14532

Manufacturer:

onsemi

Product Status:

Active

Circuit:

1 x 8:3

Current - Output High, Low:

8.8mA, 8.8mA

Voltage - Supply:

3V ~ 18V

Mounting Type:

Surface Mount

Supplier Device Package:

16-SOIC

Environmental & Export classification

RoHS Status:

ROHS3 Compliant

REACH Status:

REACH Unaffected

HTSUS:

8542.39.0001

Moisture Sensitivity Level (MSL):

1 (Unlimited)

ECCN:

EAR99

MC14532B

8-Bit Priority Encoder

The MC14532B is constructed with complementary MOS (CMOS) enhancement mode devices. The primary function of a priority encoder is to provide a binary address for the active input with the highest priority. Eight data inputs (D0 thru D7) and an enable input (E_{in}) are provided. Five outputs are available, three are address outputs (Q0 thru Q2), one group select (GS) and one enable output (E_{out}).

Features

- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Capable of Driving Two Low-Power TTL Loads or One Low-Power Schottky TTL Load over the Rated Temperature Range
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- This Device is Pb-Free and is RoHS Compliant

MAXIMUM RATINGS (Voltages Referenced to V_{SS})

Rating	Symbol	Value	Unit
DC Supply Voltage Range	V_{DD}	-0.5 to +18.0	V
Input or Output Voltage Range (DC or Transient)	V_{in} , V_{out}	-0.5 to $V_{DD} + 0.5$	V
Input or Output Current (DC or Transient) per Pin	I_{in} , I_{out}	± 10	mA
Power Dissipation, per Package (Note 1)	P_D	500	mW
Ambient Temperature Range	T_A	-55 to +125	$^{\circ}C$
Storage Temperature Range	T_{stg}	-65 to +150	$^{\circ}C$
Lead Temperature (8 Sec Soldering)	T_L	260	$^{\circ}C$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Temperature Derating: "D/DW" Package: -7.0 mW/ $^{\circ}C$ From 65 $^{\circ}C$ To 125 $^{\circ}C$

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either V_{SS} or V_{DD}). Unused outputs must be left open.

TRUTH TABLE

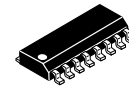
Input									Output				
E_{in}	D7	D6	D5	D4	D3	D2	D1	D0	GS	Q2	Q1	Q0	E_{out}
0	X	X	X	X	X	X	X	X	0	0	0	0	0
1	0	0	0	0	0	0	0	0	0	0	0	0	1
1	1	X	X	X	X	X	X	X	1	1	1	1	0
1	0	1	X	X	X	X	X	X	1	1	1	0	0
1	0	0	1	X	X	X	X	X	1	1	0	1	0
1	0	0	0	1	X	X	X	X	1	1	0	0	0
1	0	0	0	0	1	X	X	X	1	0	1	1	0
1	0	0	0	0	0	1	X	X	1	0	1	0	0
1	0	0	0	0	0	0	1	X	1	0	0	1	0
1	0	0	0	0	0	0	0	1	1	0	0	0	0

X = Don't Care



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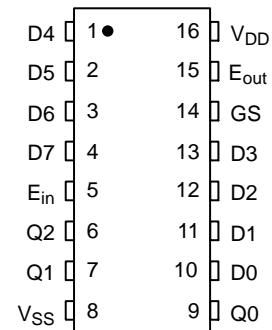
<http://onsemi.com>



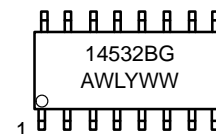
1

SOIC-16
D SUFFIX
CASE 751B

PIN ASSIGNMENT



MARKING DIAGRAM



A = Assembly Location
WL = Wafer Lot
YY, Y = Year
WW = Work Week
G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

MC14532B**ORDERING INFORMATION**

Device	Package	Shipping†
MC14532BDG	SOIC-16 (Pb-Free)	48 Units / Rail
MC14532BDR2G	SOIC-16 (Pb-Free)	2500 / Tape & Reel
NLV14532BDR2G*	SOIC-16 (Pb-Free)	2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

ELECTRICAL CHARACTERISTICS (Voltages Referenced to V_{SS})

Characteristic	Symbol	V_{DD} Vdc	- 55° C		25° C			125° C		Unit
			Min	Max	Min	Typ (Note 2)	Max	Min	Max	
Output Voltage $V_{in} = V_{DD}$ or 0	"0" Level V_{OL}	5.0	-	0.05	-	0	0.05	-	0.05	Vdc
		10	-	0.05	-	0	0.05	-	0.05	
15		-	0.05	-	0	0.05	-	0.05		
$V_{in} = 0$ or V_{DD}	"1" Level V_{OH}	5.0	4.95	-	4.95	5.0	-	4.95	-	Vdc
		10	9.95	-	9.95	10	-	9.95	-	
		15	14.95	-	14.95	15	-	14.95	-	
Input Voltage ($V_O = 4.5$ or 0.5 Vdc) ($V_O = 9.0$ or 1.0 Vdc) ($V_O = 13.5$ or 1.5 Vdc)	"0" Level V_{IL}	5.0	-	1.5	-	2.25	1.5	-	1.5	Vdc
		10	-	3.0	-	4.50	3.0	-	3.0	
15		-	4.0	-	6.75	4.0	-	4.0		
$V_O = 0.5$ or 4.5 Vdc) ($V_O = 1.0$ or 9.0 Vdc) ($V_O = 1.5$ or 13.5 Vdc)	"1" Level V_{IH}	5.0	3.5	-	3.5	2.75	-	3.5	-	Vdc
		10	7.0	-	7.0	5.50	-	7.0	-	
		15	11	-	11	8.25	-	11	-	
Output Drive Current ($V_{OH} = 2.5$ Vdc) ($V_{OH} = 4.6$ Vdc) ($V_{OH} = 9.5$ Vdc) ($V_{OH} = 13.5$ Vdc)	Source I_{OH}	5.0	-3.0	-	-2.4	-4.2	-	-1.7	-	mAdc
		5.0	-0.64	-	-0.51	-0.88	-	-0.36	-	
		10	-1.6	-	-1.3	-2.25	-	-0.9	-	
		15	-4.2	-	-3.4	-8.8	-	-2.4	-	
$V_{OL} = 0.4$ Vdc) ($V_{OL} = 0.5$ Vdc) ($V_{OL} = 1.5$ Vdc)	Sink I_{OL}	5.0	0.64	-	0.51	0.88	-	0.36	-	mAdc
		10	1.6	-	1.3	2.25	-	0.9	-	
		15	4.2	-	3.4	8.8	-	2.4	-	
Input Current	I_{in}	15	-	±0.1	-	±0.00001	±0.1	-	±1.0	µAdc
Input Capacitance ($V_{in} = 0$)	C_{in}	-	-	-	-	5.0	7.5	-	-	pF
Quiescent Current (Per Package)	I_{DD}	5.0	-	5.0	-	0.005	5.0	-	150	µAdc
		10	-	10	-	0.010	10	-	300	
		15	-	20	-	0.015	20	-	600	
Total Supply Current (Notes 3, 4) (Dynamic plus Quiescent, Per Package) ($C_L = 50$ pF on all outputs, all buffers switching)	I_T	5.0	$I_T = (1.74 \mu\text{A}/\text{kHz}) f + I_{DD}$							µAdc
10	$I_T = (3.65 \mu\text{A}/\text{kHz}) f + I_{DD}$									
15	$I_T = (5.73 \mu\text{A}/\text{kHz}) f + I_{DD}$									

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

2. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

3. The formulas given are for the typical characteristics only at 25°C.

4. To calculate total supply current at loads other than 50 pF:

$$I_T(C_L) = I_T(50 \text{ pF}) + (C_L - 50) V f k$$

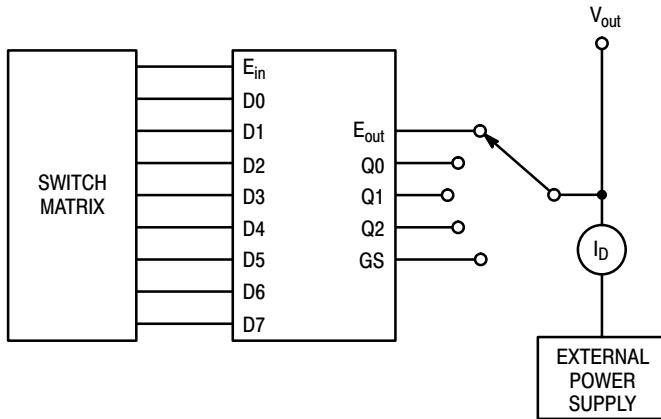
where: I_T is in µA (per package), C_L in pF, $V = (V_{DD} - V_{SS})$ in volts, f in kHz is input frequency, and $k = 0.005$.

MC14532B

SWITCHING CHARACTERISTICS (C_L = 50 pF, T_A = 25°C) (Note 5)

Characteristic	Symbol	V _{DD}	Min	Typ (Note 6)	Max	Unit
Output Rise and Fall Time t _{TLH} , t _{THL} = (1.5 ns/pF) C _L + 25 ns t _{TLH} , t _{THL} = (0.75 ns/pF) C _L + 12.5 ns t _{TLH} , t _{THL} = (0.55 ns/pF) C _L + 9.5 ns	t _{TLH} , t _{THL}	5.0 10 15	- - -	100 50 40	200 100 80	ns
Propagation Delay Time — E _{in} to E _{out} t _{PLH} , t _{PHL} = (1.7 ns/pF) C _L + 120 ns t _{PLH} , t _{PHL} = (0.66 ns/pF) C _L + 77 ns t _{PLH} , t _{PHL} = (0.5 ns/pF) C _L + 55 ns	t _{PLH} , t _{PHL}	5.0 10 15	- - -	205 110 80	410 220 160	ns
Propagation Delay Time — E _{in} to GS t _{PLH} , t _{PHL} = (1.7 ns/pF) C _L + 90 ns t _{PLH} , t _{PHL} = (0.66 ns/pF) C _L + 57 ns t _{PLH} , t _{PHL} = (0.5 ns/pF) C _L + 40 ns	t _{PLH} , t _{PHL}	5.0 10 15	- - -	175 90 65	350 180 130	ns
Propagation Delay Time — E _{in} to Q _n t _{PLH} , t _{PHL} = (1.7 ns/pF) C _L + 195 ns t _{PLH} , t _{PHL} = (0.66 ns/pF) C _L + 107 ns t _{PLH} , t _{PHL} = (0.5 ns/pF) C _L + 75 ns	t _{PHL} , t _{PLH}	5.0 10 15	- - -	280 140 100	560 280 200	ns
Propagation Delay Time — D _n to Q _n t _{PLH} , t _{PHL} = (1.7 ns/pF) C _L + 265 ns t _{PLH} , t _{PHL} = (0.66 ns/pF) C _L + 137 ns t _{PLH} , t _{PHL} = (0.5 ns/pF) C _L + 85 ns	t _{PLH} , t _{PHL}	5.0 10 15	- - -	300 170 110	600 340 220	ns
Propagation Delay Time — D _n to GS t _{PLH} , t _{PHL} = (1.7 ns/pF) C _L + 195 ns t _{PLH} , t _{PHL} = (0.66 ns/pF) C _L + 107 ns t _{PLH} , t _{PHL} = (0.5 ns/pF) C _L + 75 ns	t _{PLH} , t _{PHL}	5.0 10 15	- - -	280 140 100	560 280 200	ns

5. The formulas given are for the typical characteristics only at 25°C.
 6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.



Output Under Test	V _{GS} = V _{DD} V _{DS} = V _{out} Sink Current		V _{GS} = -V _{DD} V _{DS} = V _{out} - V _{DD} Source Current		
	D0 thru D7	E _{in}	D0 thru D6	D7	E _{in}
E _{out}	X	0	0	0	1
Q0	X	0	0	1	1
Q1	X	0	0	1	1
Q2	X	0	0	1	1
GS	X	0	0	1	1

Figure 1. Typical Sink and Source Current Characteristics

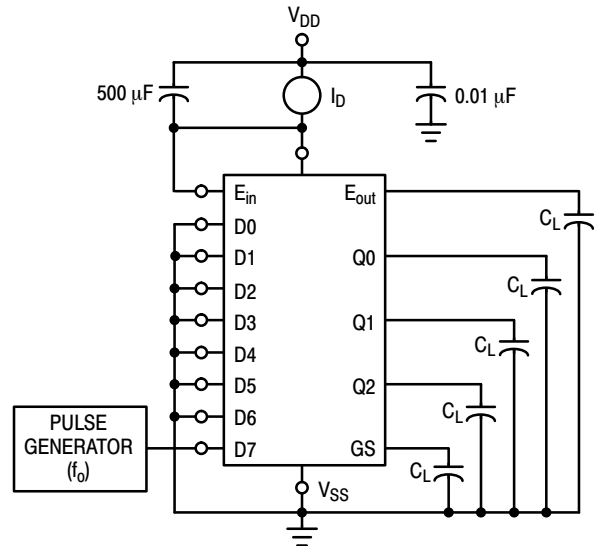


Figure 2. Typical Power Dissipation Test Circuit

MC14532B

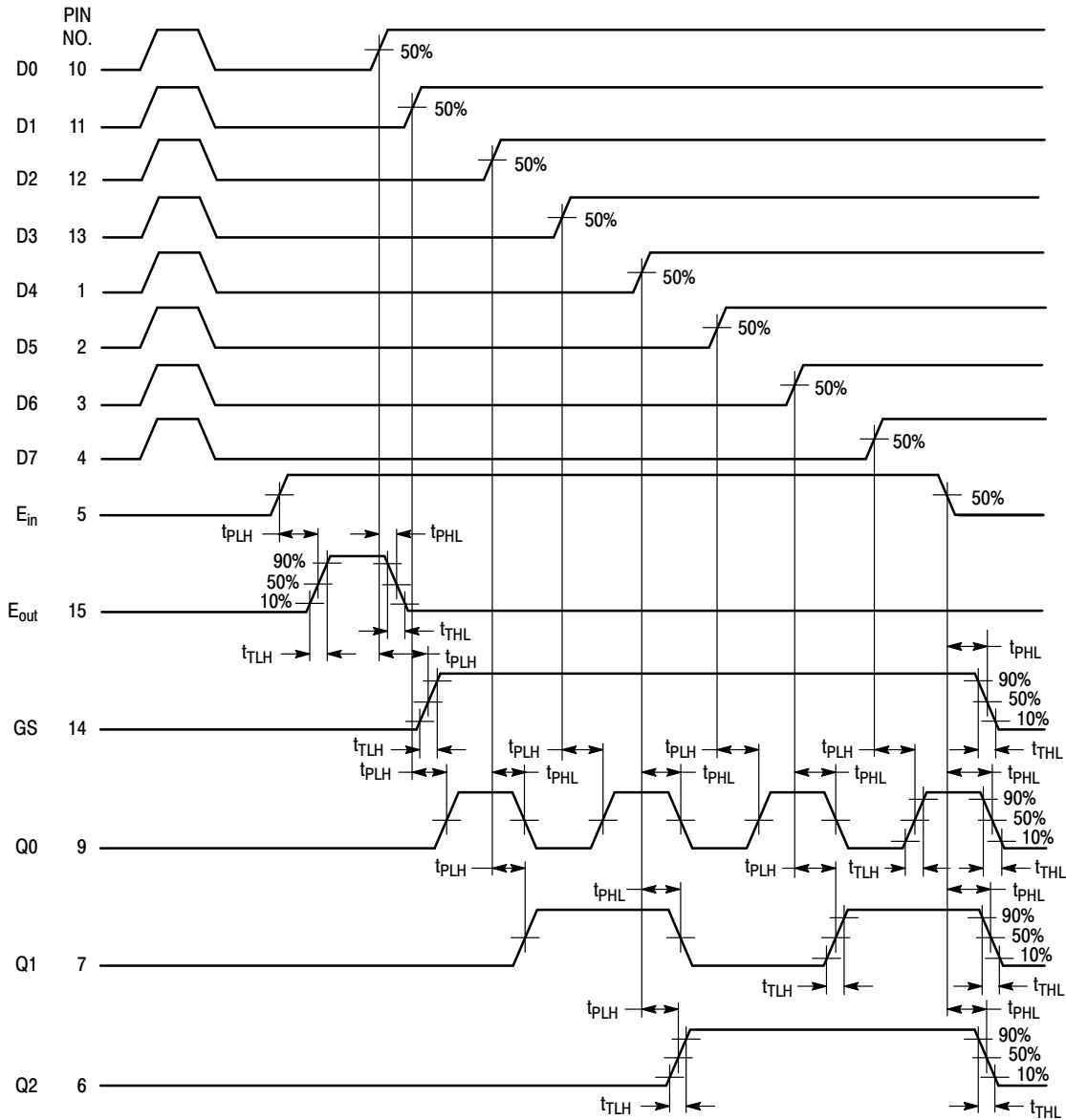
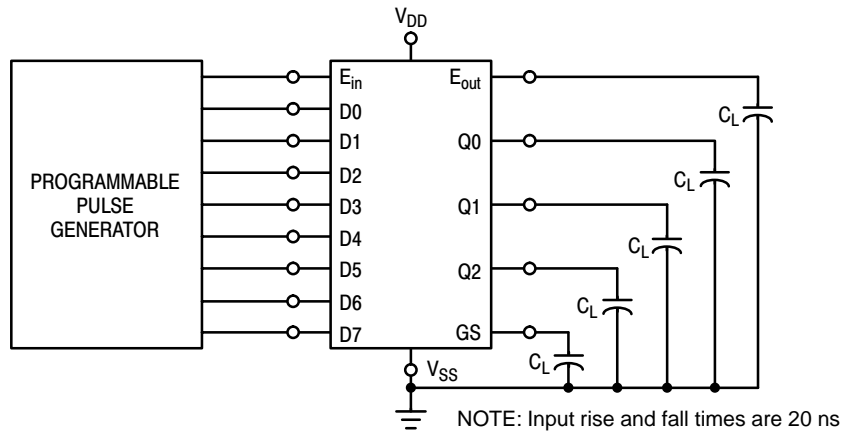


Figure 3. AC Test Circuit and Waveforms

MC14532B

LOGIC EQUATIONS

$$E_{out} = E_{in} \cdot \bar{D}0 \cdot \bar{D}1 \cdot \bar{D}2 \cdot \bar{D}3 \cdot \bar{D}4 \cdot \bar{D}5 \cdot \bar{D}6 \cdot \bar{D}7$$

$$Q0 = E_{in} \cdot (D1 \cdot \bar{D}2 \cdot \bar{D}4 \cdot \bar{D}6 + D3 \cdot \bar{D}4 \cdot \bar{D}6 + D5 \cdot \bar{D}6 + D7)$$

$$Q1 = E_{in} \cdot (D2 \cdot \bar{D}4 \cdot \bar{D}5 + D3 \cdot \bar{D}4 \cdot \bar{D}5 + D6 + D7)$$

$$Q2 = E_{in} \cdot (D4 + D5 + D6 + D7)$$

$$GS = E_{in} \cdot (D0 + D1 + D2 + D3 + D4 + D5 + D6 + D7)$$

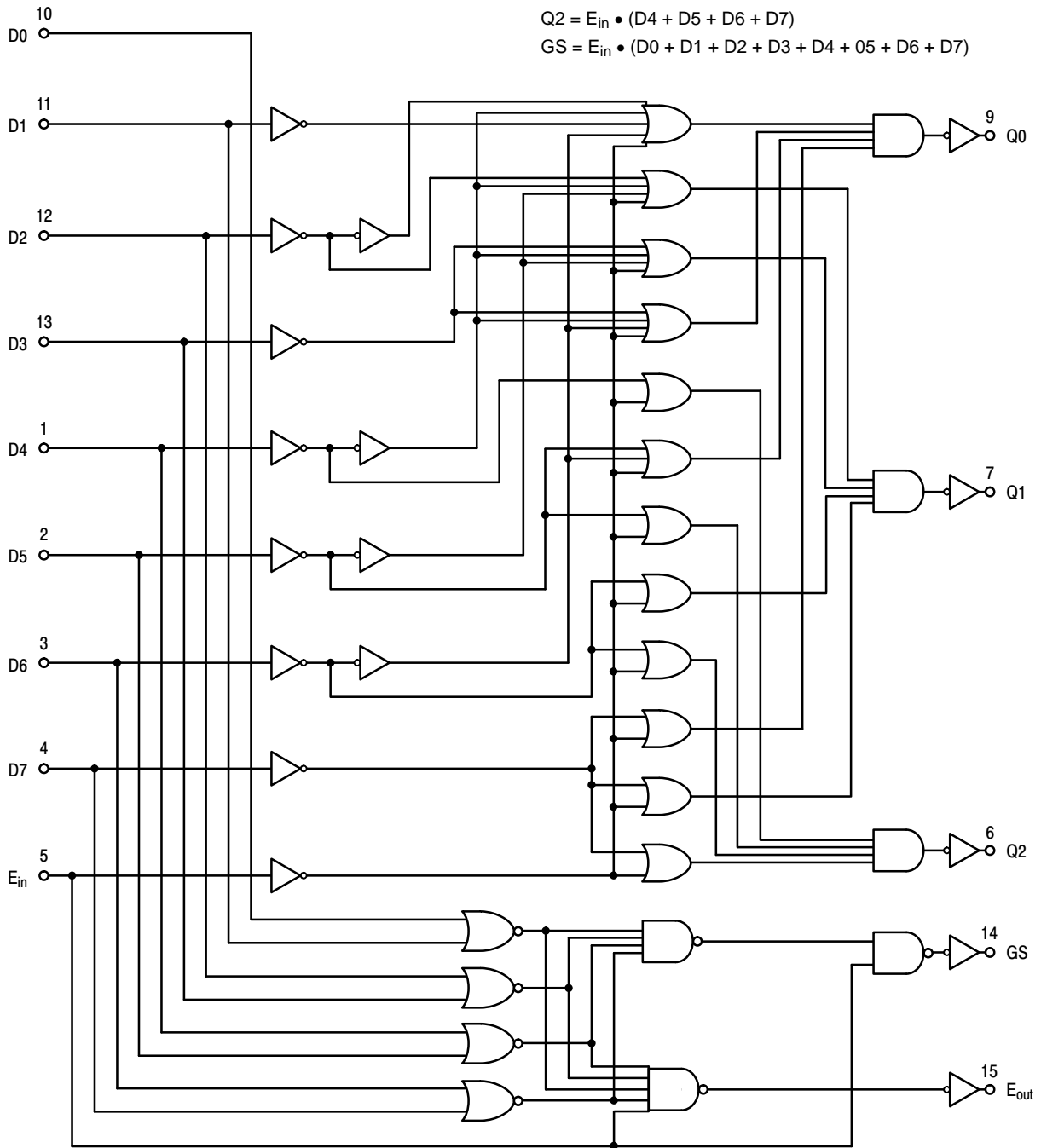


Figure 4. Logic Diagram
(Positive Logic)

MC14532B

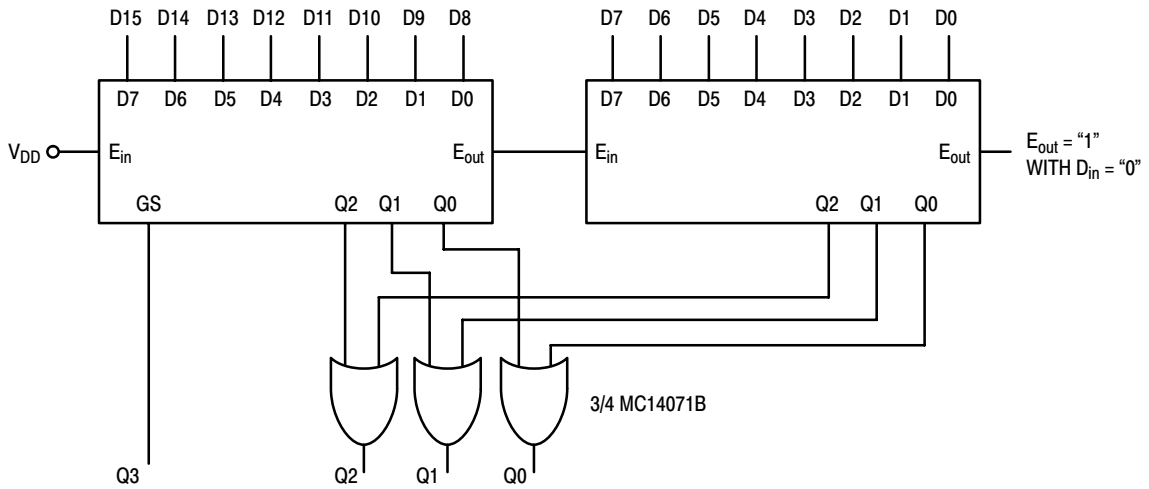


Figure 5. Two MC14532B's Cascaded for 4–Bit Output

DIGITAL TO ANALOG CONVERSION

The digital eight-bit word to be converted is applied to the inputs of the MC14512 with the most significant bit at X7 and the least significant bit at X0. A clock input of up to 2.5 MHz (at $V_{DD} = 10\text{ V}$) is applied to the MC14520B. A compromise between I_{bias} for the MC1710 and ΔR between N and P-channel outputs gives a value of R of 33 k Ω . In order to filter out the switching frequencies, RC should be about 1.0 ms (if $R = 33\text{ k}\Omega$, $C \approx 0.03\text{ }\mu\text{F}$). The analog 3.0 dB bandwidth would then be dc to 1.0 kHz.

ANALOG TO DIGITAL CONVERSION

An analog signal is applied to the analog input of the MC1710. A digital eight-bit word known to represent a digitized level less than the analog input is applied to the MC14512 as in the D to A conversion. The word is incremented at rates sufficient to allow steady state to be reached between incrementations (i.e. 3.0 ms). The output of the MC1710 will change when the digital input represents the first digitized level above the analog input. This word is the digital representation of the analog word.

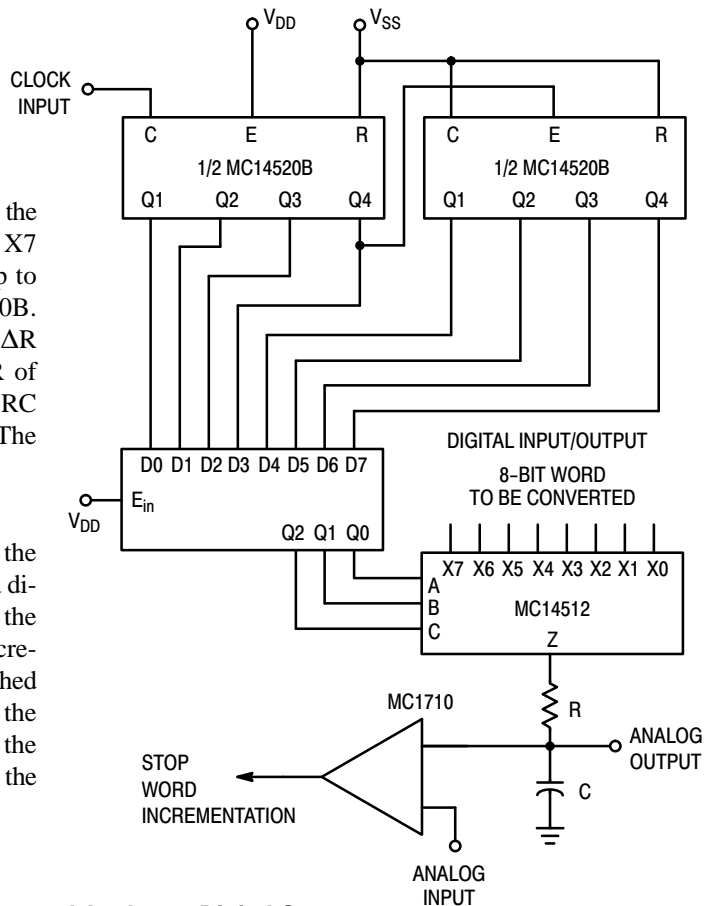
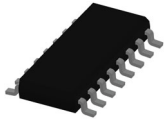


Figure 6. Digital to Analog and Analog to Digital Converter



**MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS**

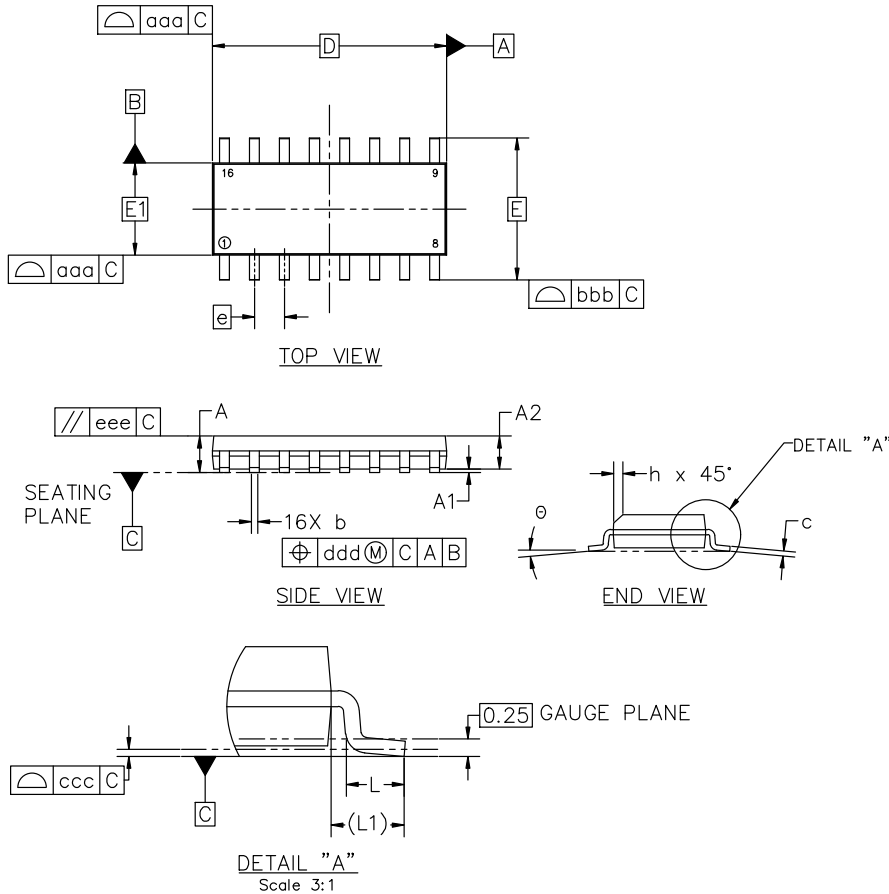


**SOIC-16 9.90x3.90x1.37 1.27P
CASE 751B
ISSUE M**

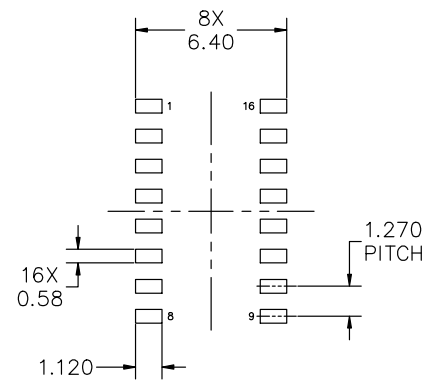
DATE 18 OCT 2024

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.
2. DIMENSION IN MILLIMETERS. ANGLE IN DEGREES.
3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15mm PER SIDE.
5. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127mm TOTAL IN EXCESS OF THE b DIMENSION AT MAXIMUM MATERIAL CONDITION.



MILLIMETERS			
DIM	MIN	NOM	MAX
A	1.35	1.55	1.75
A1	0.10	0.18	0.25
A2	1.25	1.37	1.50
b	0.35	0.42	0.49
c	0.19	0.22	0.25
D	9.90 BSC		
E	6.00 BSC		
E1	3.90 BSC		
e	1.27 BSC		
h	0.25	---	0.50
L	0.40	0.83	1.25
L1	1.05 REF		
θ	0°	---	7°
TOLERANCE OF FORM AND POSITION			
aaa	0.10		
bbb	0.20		
ccc	0.10		
ddd	0.25		
eee	0.10		



RECOMMENDED MOUNTING FOOTPRINT

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE onsemi SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D

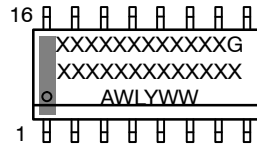
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DESCRIPTION:	SOIC-16 9.90X3.90X1.37 1.27P	PAGE 1 OF 2

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SOIC-16 9.90x3.90x1.37 1.27P
CASE 751B
ISSUE M

DATE 18 OCT 2024

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code
 A = Assembly Location
 WL = Wafer Lot
 Y = Year
 WW = Work Week
 G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

<p>STYLE 1:</p> <p>PIN 1. COLLECTOR 2. BASE 3. EMITTER 4. NO CONNECTION 5. EMITTER 6. BASE 7. COLLECTOR 8. COLLECTOR 9. BASE 10. EMITTER 11. NO CONNECTION 12. EMITTER 13. BASE 14. COLLECTOR 15. EMITTER 16. COLLECTOR</p>	<p>STYLE 2:</p> <p>PIN 1. CATHODE 2. ANODE 3. NO CONNECTION 4. CATHODE 5. CATHODE 6. NO CONNECTION 7. ANODE 8. CATHODE 9. CATHODE 10. ANODE 11. NO CONNECTION 12. CATHODE 13. CATHODE 14. NO CONNECTION 15. ANODE 16. CATHODE</p>	<p>STYLE 3:</p> <p>PIN 1. COLLECTOR, DYE #1 2. BASE, #1 3. EMITTER, #1 4. COLLECTOR, #1 5. COLLECTOR, #2 6. BASE, #2 7. EMITTER, #2 8. COLLECTOR, #2 9. COLLECTOR, #3 10. BASE, #3 11. EMITTER, #3 12. COLLECTOR, #3 13. COLLECTOR, #4 14. BASE, #4 15. EMITTER, #4 16. COLLECTOR, #4</p>	<p>STYLE 4:</p> <p>PIN 1. COLLECTOR, DYE #1 2. COLLECTOR, #1 3. COLLECTOR, #2 4. COLLECTOR, #2 5. COLLECTOR, #3 6. COLLECTOR, #3 7. COLLECTOR, #4 8. COLLECTOR, #4 9. BASE, #4 10. EMITTER, #4 11. BASE, #3 12. EMITTER, #3 13. BASE, #2 14. EMITTER, #2 15. BASE, #1 16. EMITTER, #1</p>
<p>STYLE 5:</p> <p>PIN 1. DRAIN, DYE #1 2. DRAIN, #1 3. DRAIN, #2 4. DRAIN, #2 5. DRAIN, #3 6. DRAIN, #3 7. DRAIN, #4 8. DRAIN, #4 9. GATE, #4 10. SOURCE, #4 11. GATE, #3 12. SOURCE, #3 13. GATE, #2 14. SOURCE, #2 15. GATE, #1 16. SOURCE, #1</p>	<p>STYLE 6:</p> <p>PIN 1. CATHODE 2. CATHODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE 7. CATHODE 8. CATHODE 9. ANODE 10. ANODE 11. ANODE 12. ANODE 13. ANODE 14. ANODE 15. ANODE 16. ANODE</p>	<p>STYLE 7:</p> <p>PIN 1. SOURCE N-CH 2. COMMON DRAIN (OUTPUT) 3. COMMON DRAIN (OUTPUT) 4. GATE P-CH 5. COMMON DRAIN (OUTPUT) 6. COMMON DRAIN (OUTPUT) 7. COMMON DRAIN (OUTPUT) 8. SOURCE P-CH 9. SOURCE P-CH 10. COMMON DRAIN (OUTPUT) 11. COMMON DRAIN (OUTPUT) 12. COMMON DRAIN (OUTPUT) 13. GATE N-CH 14. COMMON DRAIN (OUTPUT) 15. COMMON DRAIN (OUTPUT) 16. SOURCE N-CH</p>	

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DESCRIPTION:	SOIC-16 9.90X3.90X1.37 1.27P	PAGE 2 OF 2

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